

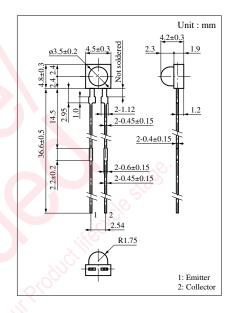
PN205L-(NC)

Darlington Phototransistor

For optical control systems

Features

- Darlington output, high sensitivity
- Easy to combine light emission and photodetection on same printed circuit board
- Small size, thin side-view type package
- Long lead and visible light cutoff design with PN205



Absolute Maximum Ratings (Ta = 25°C)

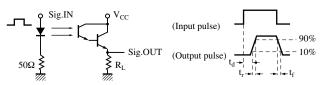
Parameter	Symbol	Ratings	Unit	
Collector to emitter voltage	V _{CEO}	20	V	
Emitter to collector voltage	V _{ECO}	5	V	
Collector current	I_{C}	30	mA	
Collector power dissipation	P _C	100	mW	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

■ Electro-Optical Characteristics (Ta = 25°C)

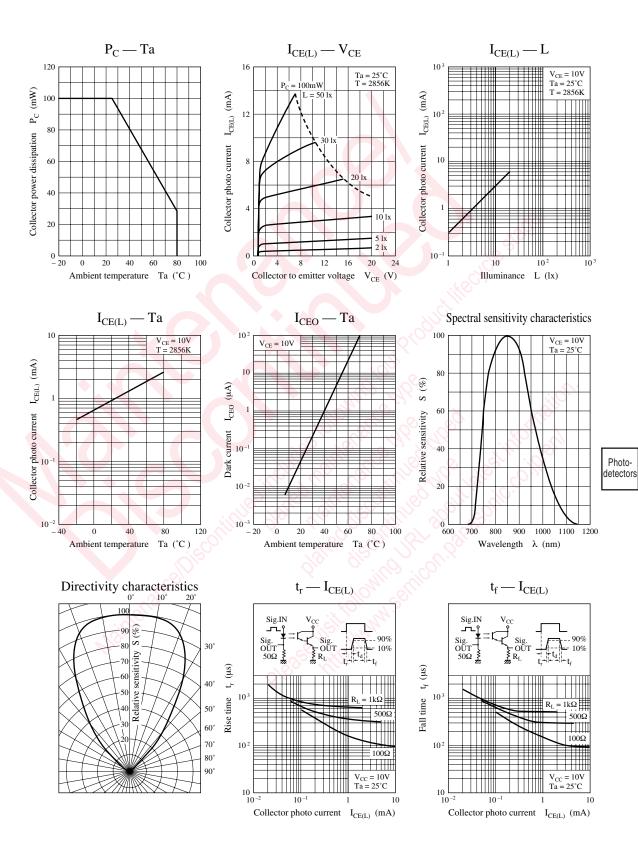
Parameter	Symbol	Conditions	min	typ	max	Unit
Dark current	I_{CEO}	$V_{CE} = 10V$),		0.5	μΑ
Sensitivity to infrared emitters	S _{IR} *1	$V_{CE} = 10V, H = 3.75 \mu W/cm^2$	0.1		3.0	mA
Peak sensitivity wavelength	$\lambda_{ m P}$	$V_{CE} = 10V$		850		nm
Acceptance half angle	θ	Measured from the optical axis to the half power point		35		deg.
Response time	t_r, t_f^{*2}	$V_{CC} = 10V, I_C = 1mA, R_L = 100\Omega$		150		μs
Collector saturation voltage	V _{CE(sat)} *1	$I_C = 100 \mu A, H = 3.75 \mu W/cm^2$			1.5	V

^{**1} Measurements were made using infrared light ($\lambda = 940 \text{ nm}$) as a light source.

^{*2} Switching time measurement circuit



- t_d: Delay time
- $t_{\rm r}$: Rise time (Time required for the collector photo current to increase from 10% to 90% of its final value)
- $t_{\rm f}$: Fall time (Time required for the collector photo current to decrease from 90% to 10% of its initial value)



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